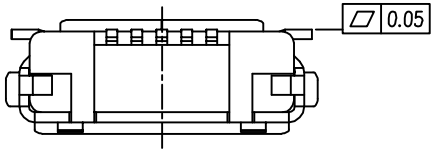
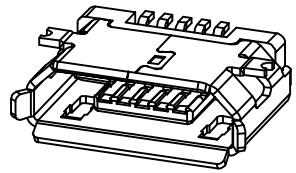
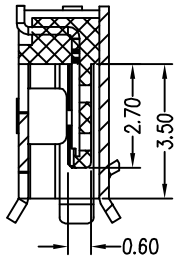
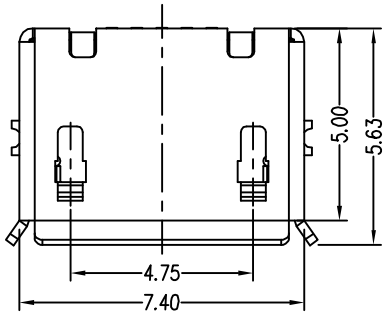
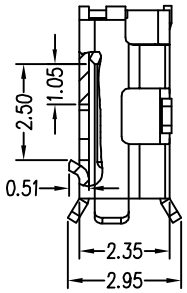
REV.	LOCAS.	DESCRIPTION	DATE	DRAWN
01		INITIAL RELEASE.		

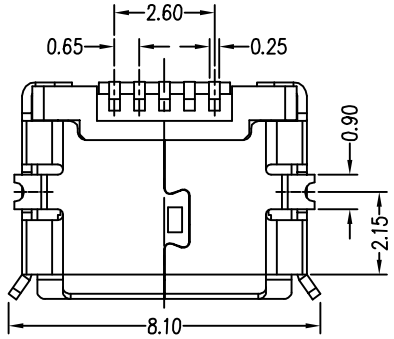


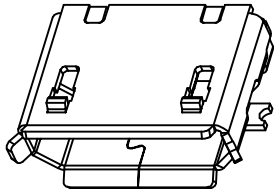


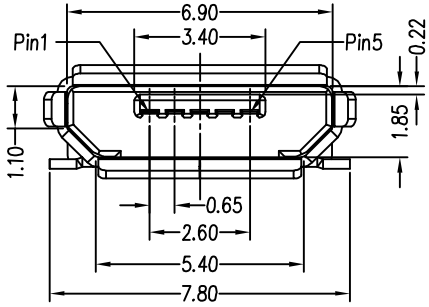


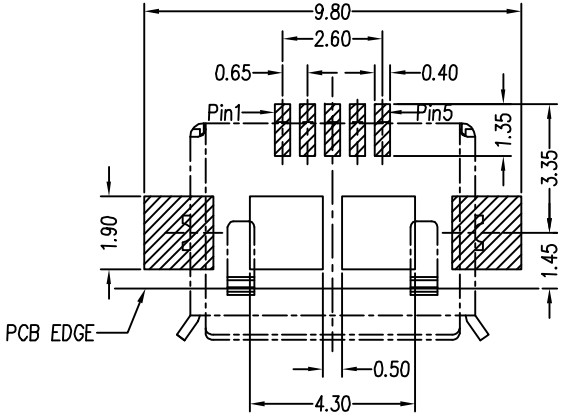












RECOMMANDED PCB LAYOUT

Note:
1.Material:
1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
1.2 Contact: copper alloy,t=0.20mm
1.3 Shell: copper alloy,t=0.25mm
2.Specification:
2.1 Current rating: 1 A Max.
2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
2.3 Contact resistance: 50 mΩ Max.
2.4 Insulation resistance: 100 MΩ Min.
2.5 Total mating force: 3.57 Kgf Max.
2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extration cycles
2.7 Temperature range: -30°C~80°C

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PART NO.	MUSB05F-78569		DRAWN	MARK			
DWG NO.			CHECK	JOHN			
TOLERANCE	X.±0.30 .X±0.25		APPROVE	MELODY			
TITLE: Micro USB 5F smt without pegs	REV. A0	.XX±0.15 .XXX±0.10	SCALE	1:1	UNIT	mm	NO	DESCRIPTION